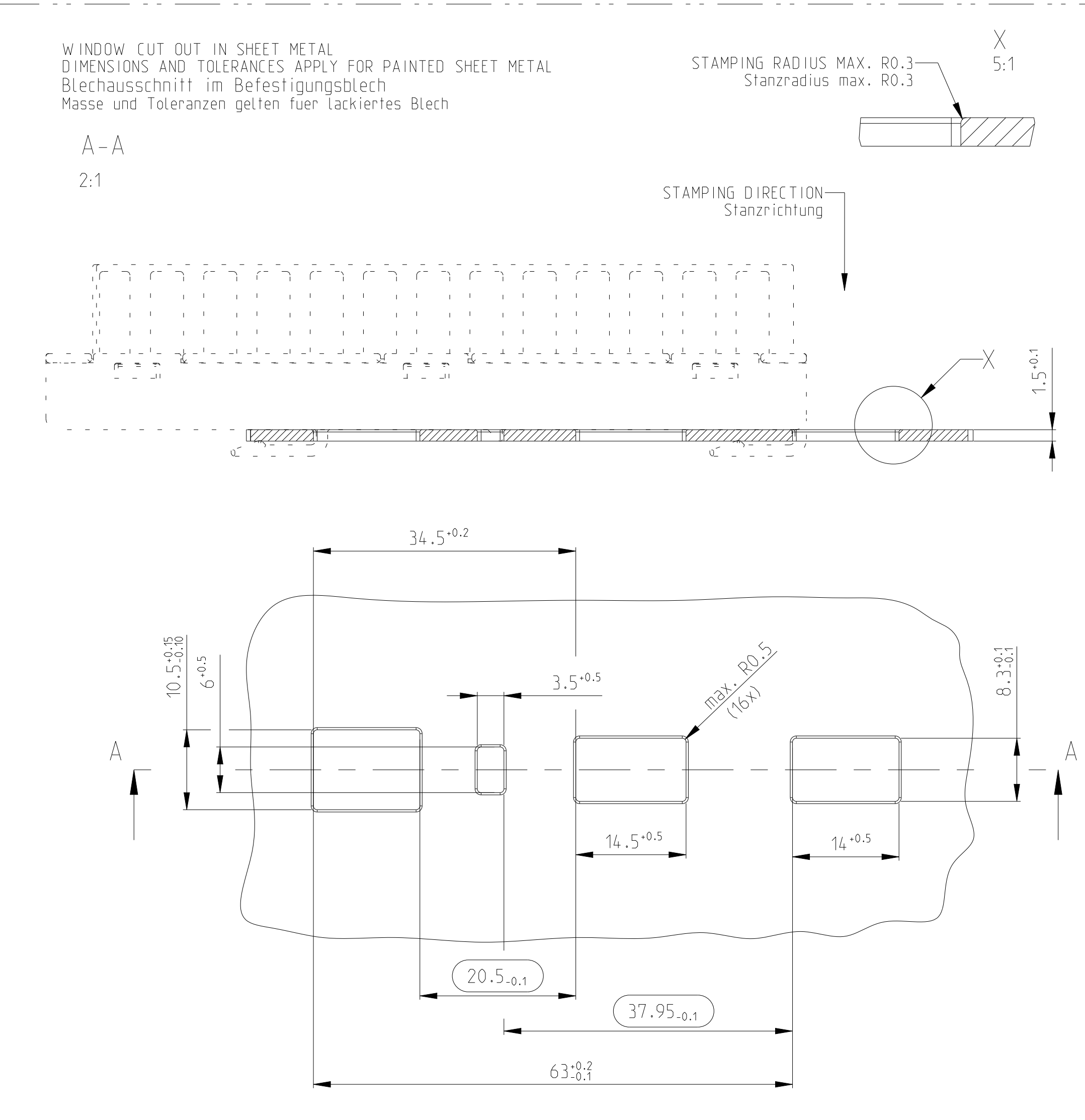
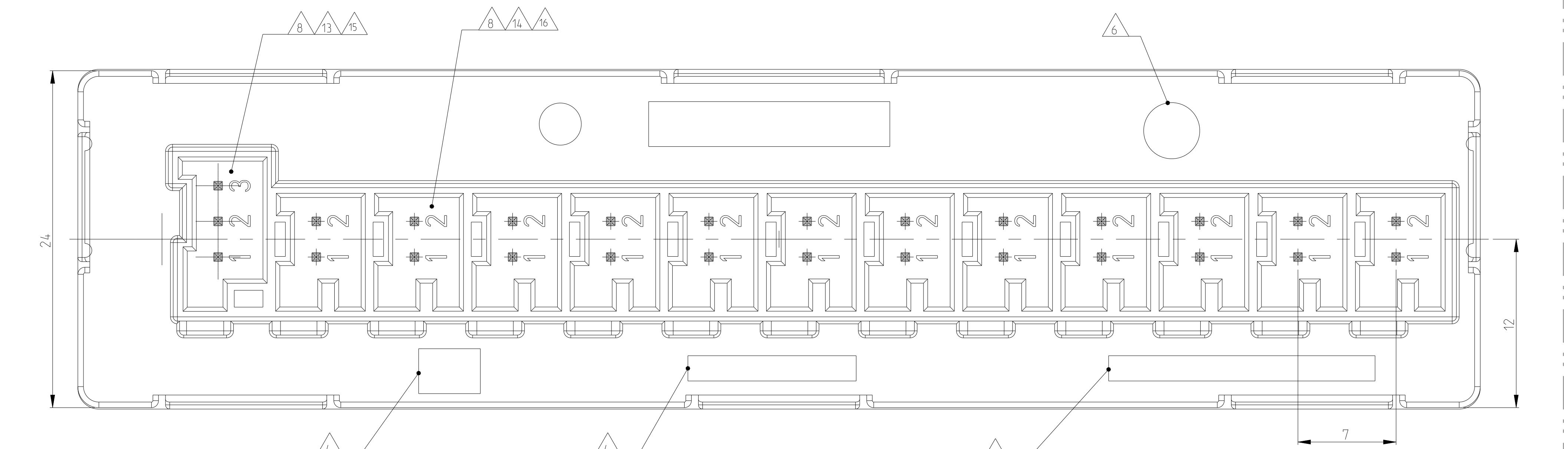
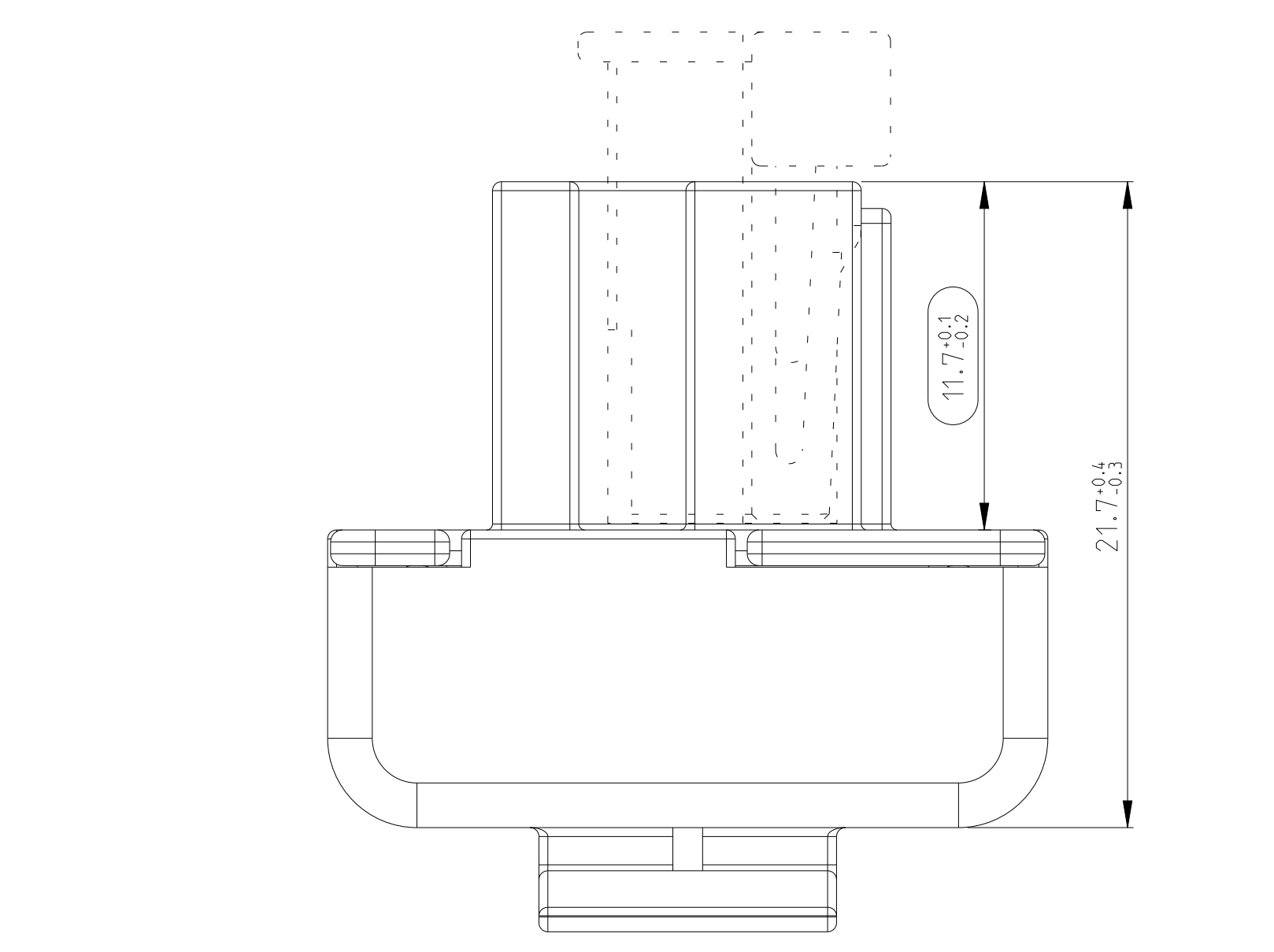
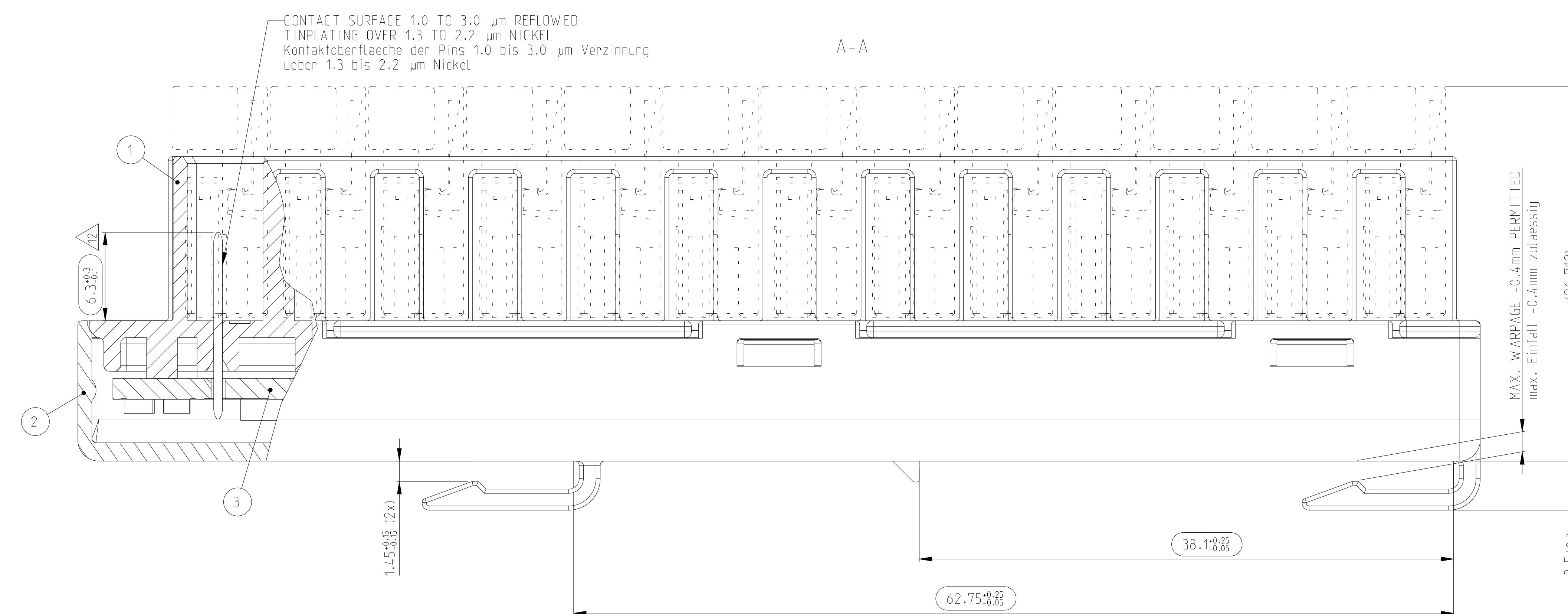
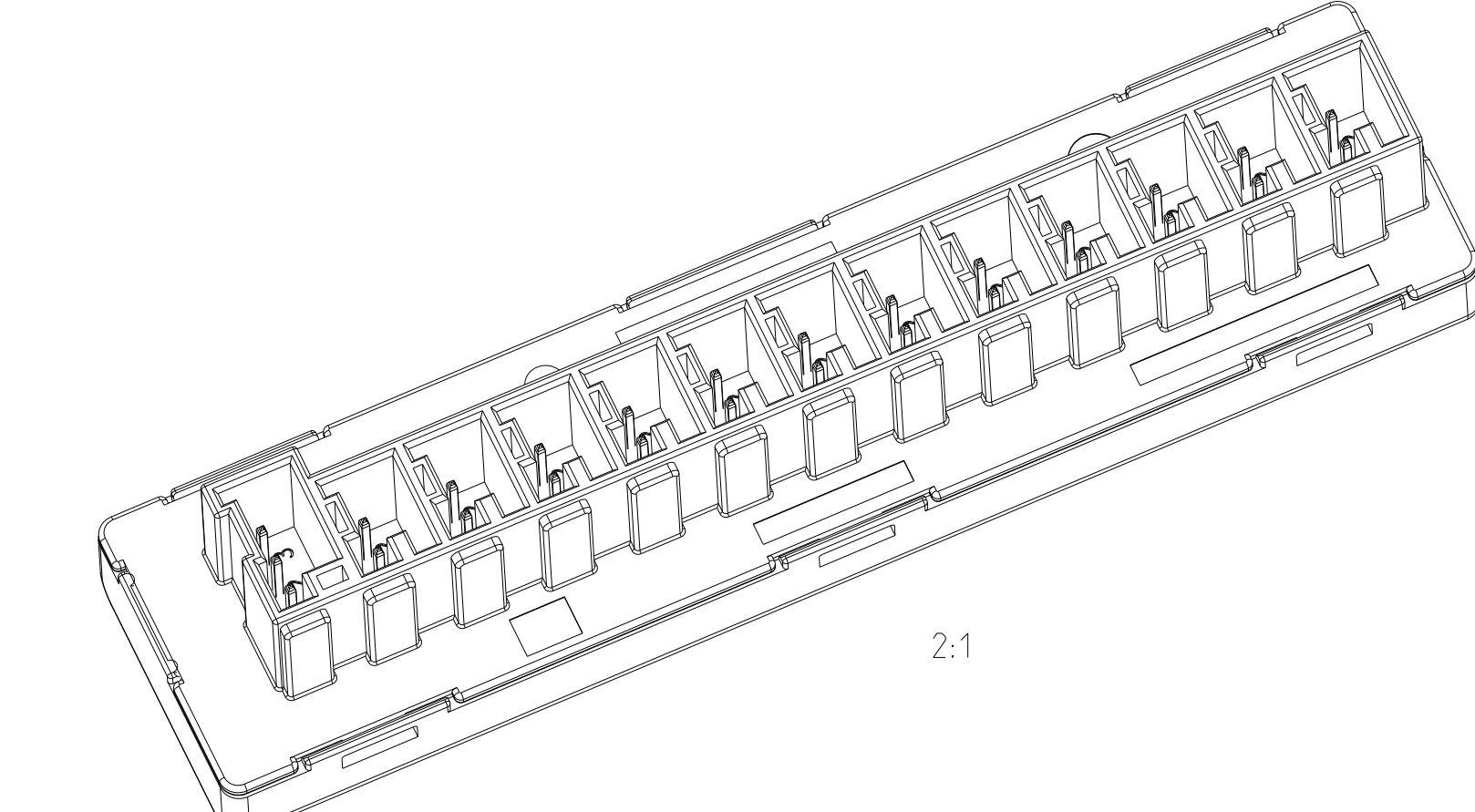
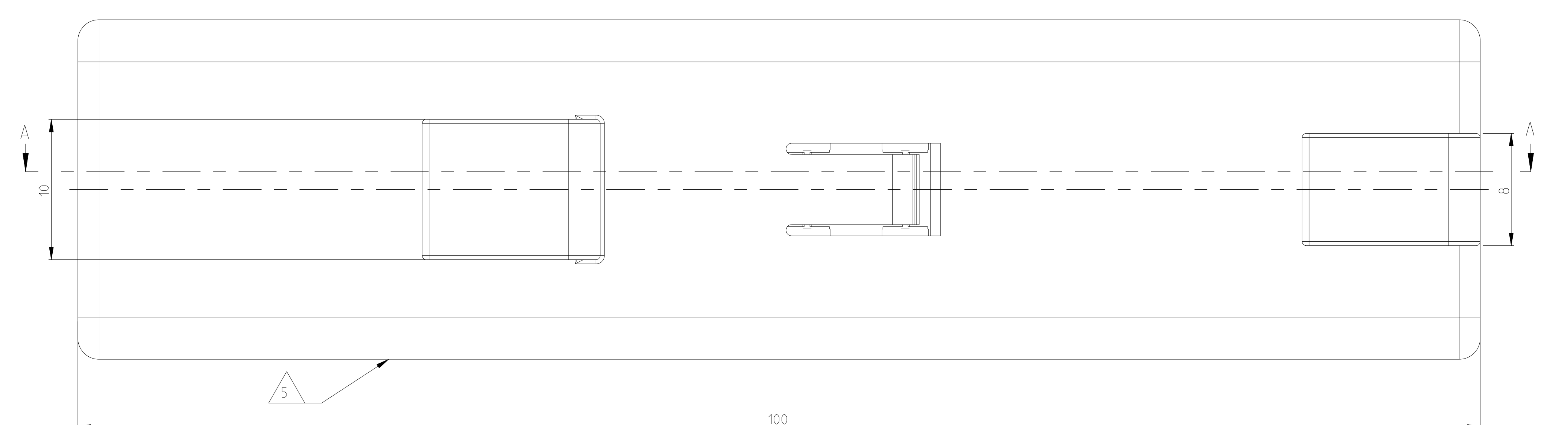
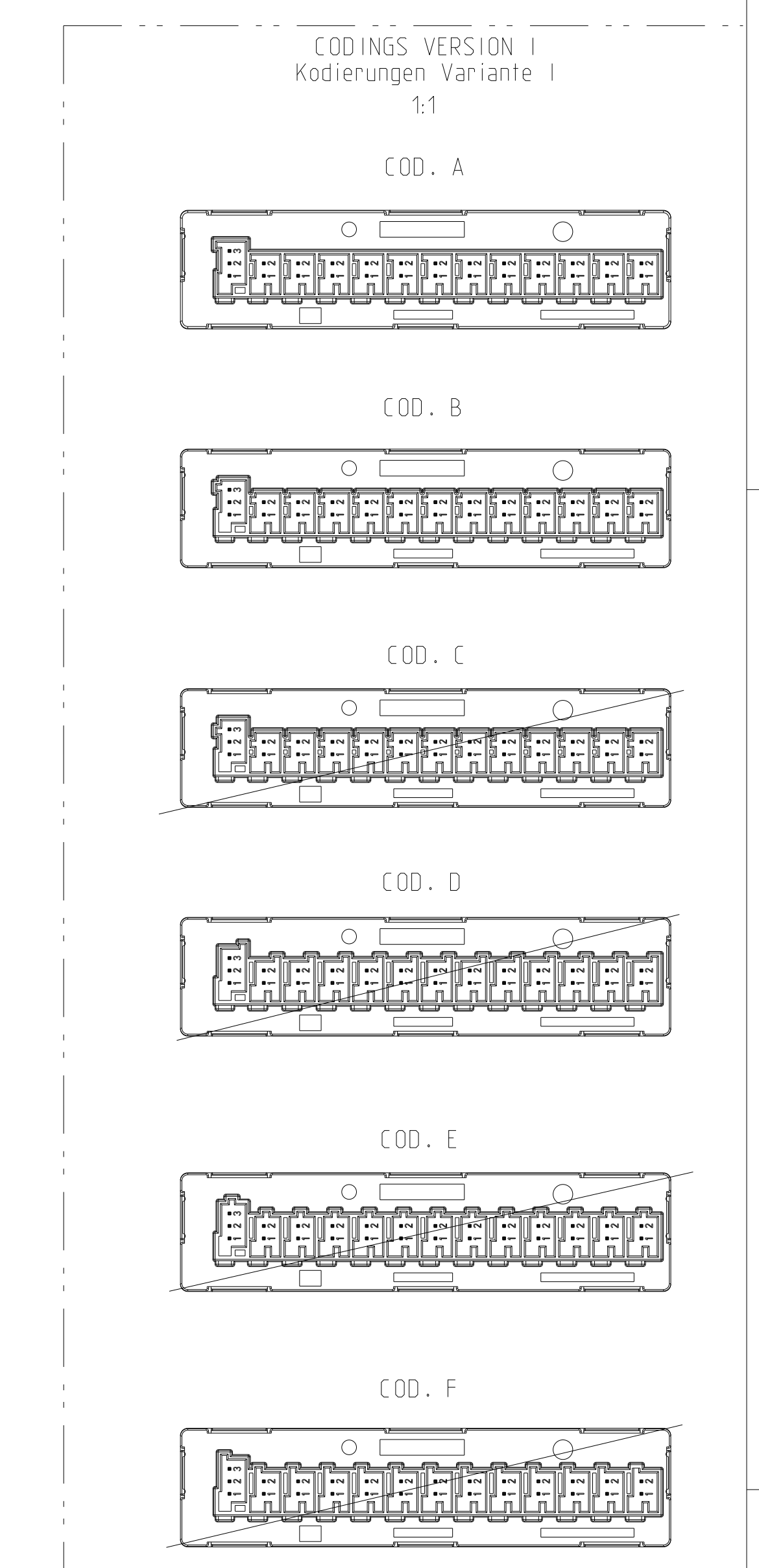


| LOC | DIST | REV | DATE      | APPD |
|-----|------|-----|-----------|------|
| A1  | -    | A1  | 13JAN2011 | CG   |
|     |      | A2  | 02SEP2011 | CR   |
|     |      | B   | 09MAY2013 | CG   |

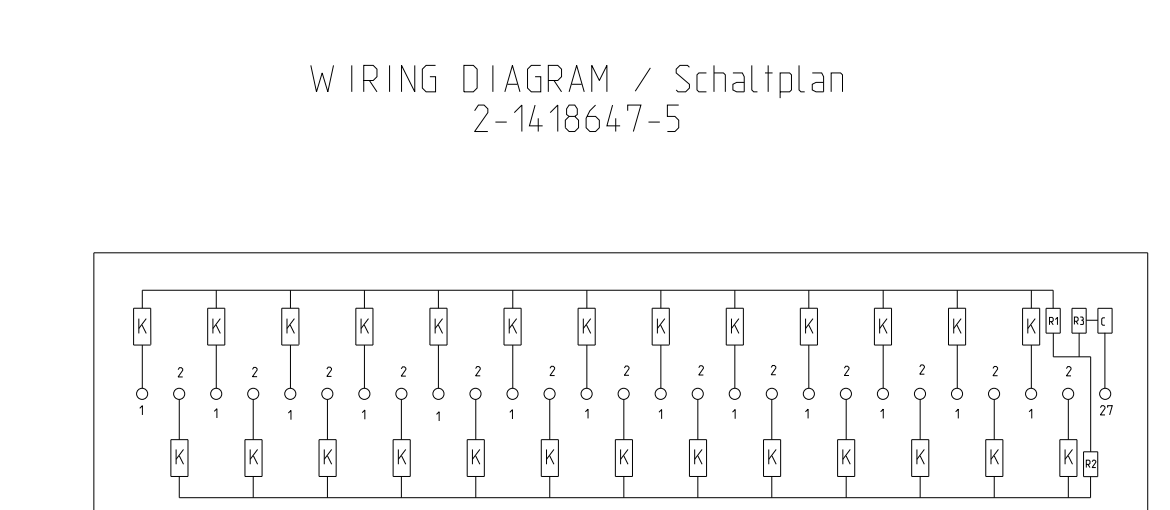
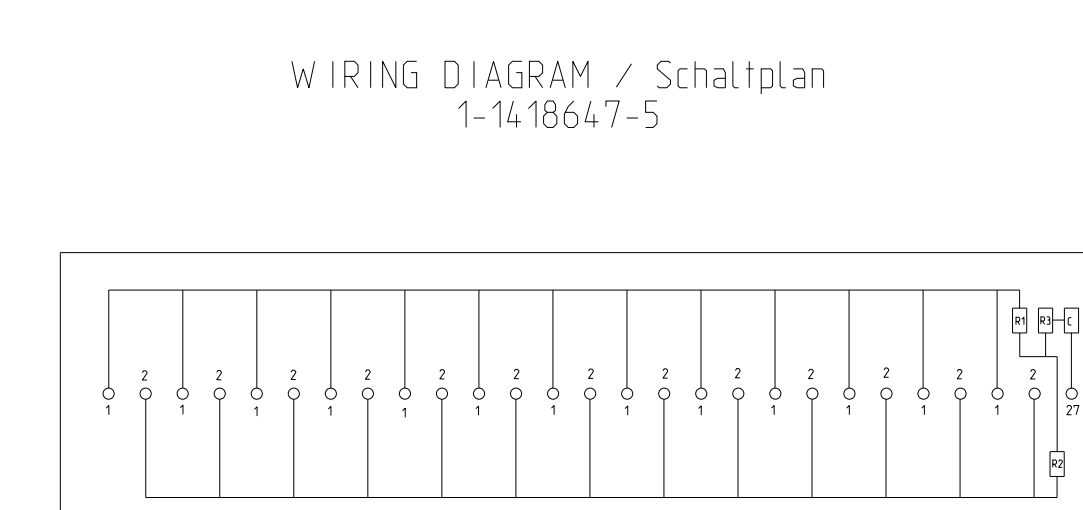
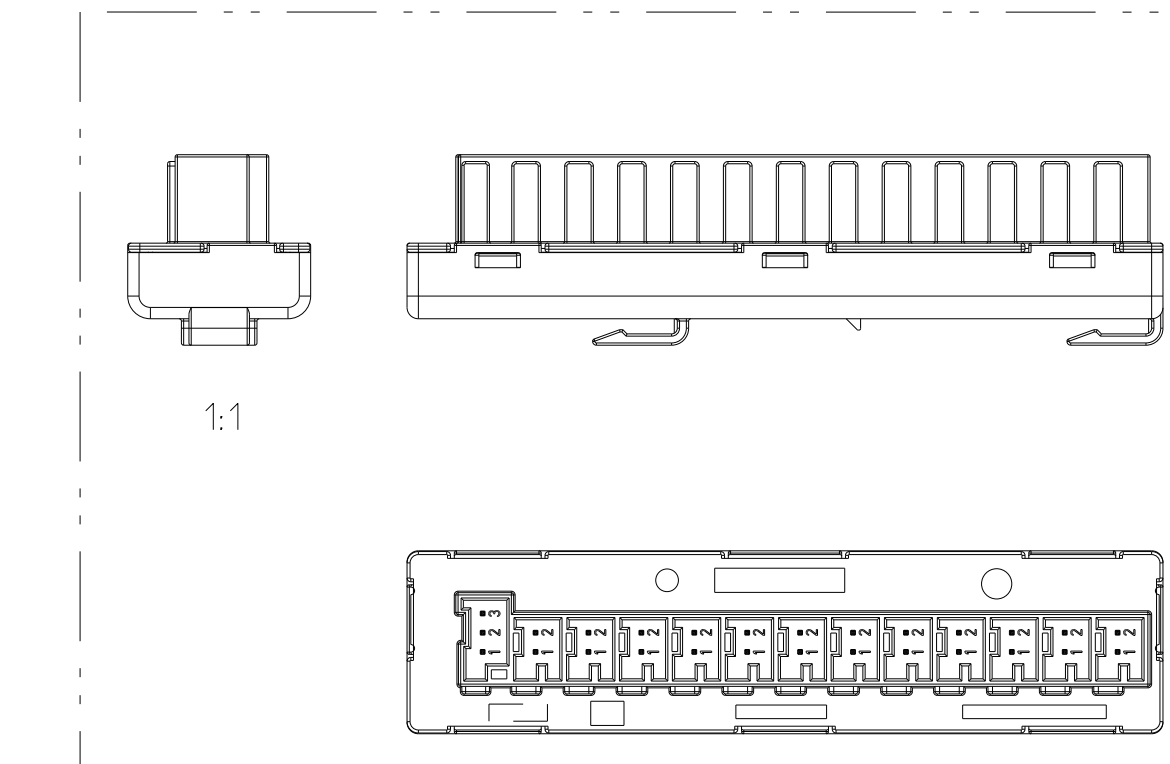


- NOTES:  
Bemerkungen:
- ONLY THE GERMAN LANGUAGE SHALL BE BINDING  
Massgebend ist der deutsche Text
  - 1- -1 AS SHOWN  
wie gezeichnet
  - FUNCTIONAL MEASUREMENTS MARKED WITH ARE DOCUMENTED IN THE PPFB. NOT MARKED MEASUREMENTS ARE MEASURED, BUT NOT DOCUMENTED IN THE PPFB. DEVIATIONS HAVE TO BE CORRECTED.  
Funktionsbestimmende Masse, die mit gekennzeichnet sind, werden im PPFB dokumentiert. Nicht gekennzeichnete Masse werden ebenfalls gemessen, aber nicht im PPFB dokumentiert. Abweichungen sind zu korrigieren.
  - SUPPLIER MARK  
Lieferantenkennzeichnung
  - MANUFACTURING IDENTIFIER  
Herstellungskennung
  - DATE INSERT  
Datumstempel
  - MATERIAL IDENTIFICATION  
Materialkennzeichnung
  - CODINGS ACCORDING TO THE CODING DESIGNATION OF THE SPECIFICATION AND THE SUITABLE SOCKET HOUSINGS.  
Kodierungen entsprechen den Kodierungsbezeichnungen der AV und der zugehörigen Buchsengehäuse.
  - SMD-PARTS ON PRINTED CIRCUIT BOARD:  
RESISTORS:  
R1 AND R2 = 56-64 Ω ±1%, 750 mW; R3 = 10 Ω ±5% 200 mW  
CONDENSER: C1 = 47 nF  
FERRIT (CHIPS): K = TDK MHF2012FRC570ATD25  
SMD-Bauteile auf der Leiterplatte:  
Widerstände:  
R1 und R2 = 56-64 Ω ±1%, 750 mW; R3 = 10 Ω ±5% 200 mW  
Kondensator: C1 = 47 nF  
Ferritkerne: K = TDK MHF2012FRC570ATD25
  - SMD-PARTS ON PRINTED CIRCUIT BOARD:  
RESISTORS:  
R1 AND R2 = 28-32 Ω ±1%, 250 mW; R3 = 10 Ω ±5% 200 mW  
CONDENSER: C1 = 47 nF  
SMD-Bauteile auf der Leiterplatte:  
Widerstände:  
R1 und R2 = 28-32 Ω ±1%, 250 mW; R3 = 10 Ω ±5% 200 mW  
Kondensator: C1 = 47 nF
  - SMD-PARTS ON PRINTED CIRCUIT BOARD:  
RESISTORS:  
R1 AND R2 = 56-64 Ω ±1%, 250 mW; R3 = 10 Ω ±5% 200 mW  
CONDENSER: C1 = 47 nF  
SMD-Bauteile auf der Leiterplatte:  
Widerstände:  
R1 und R2 = 56-64 Ω ±1%, 250 mW; R3 = 10 Ω ±5% 200 mW  
Kondensator: C1 = 47 nF
  - DIMENSION WAS DETERMINED DIFFERENT FROM SPECIFICATION  
114-18562 AND 114-18563  
Masse abweichend von Ausfuhrungsvorschrift 114-18562 und 114-18563 fertiggestellt



| NOTE Bem. | FEATURE Merkmal                         | TE Connectivity - No. |
|-----------|---|-----------------------|
|           | AV - INTERFACE<br>AV - Schnittstelle    | 114-18563             |
|           | AV - INTERFACE<br>AV - Schnittstelle    | 114-18562             |
|           | USEABLE SOCKET HSG<br>passende Kupplung | 1418640               |
|           | USEABLE SOCKET HSG<br>passende Kupplung | 1418639               |
|           | PRODUCT SPEC.<br>Product Spec.          | 108-18861             |

| TITLE Benennung                       | Mass (kg) MASS (kg) | COD | TE Connectivity ORDER-NO. | REV | QTY | Benennung   | MATERIAL                          | Farbe/Oberfläche COLOUR/SURFACE | ITEM |
|---------------------------------------|---------------------|-----|---------------------------|-----|-----|---|-----------------------------------|---------------------------------|------|
| Energieverteiler CAN 12x2pol./1x3pol. | 0.021               | B   | 2-1418647-5               | D   | 1   | Leiterplatte bestückt PRINTED CIRCUIT BOARD           | PA6-GFK 10/20 ultramid 830a2/8401 | gruen/GREEN                     | 1    |
|                                       |                     |     |                           | D   | 1   | Deckel COVER  | PA6-GFK 10/20 ultramid 830a2/8401 | natur/NATURE                    | 2    |
|                                       |                     |     |                           | D   | 1   | SHTWanne 12x2/1x3pol. MGS PIN HEADER 12X2/1X3POS. MGS | PA6-GFK 10/20 ultramid 830a2/8401 | gruen/GREEN                     | 1    |
| Energieverteiler CAN 12x2pol./1x3pol. | 0.021               | A   | 1-1418647-5               | C   | 1   | Leiterplatte bestückt PRINTED CIRCUIT BOARD           | PA6-GFK 10/20 ultramid 830a2/8401 | natur/NATURE                    | 3    |
|                                       |                     |     |                           | C   | 1   | Deckel COVER  | PA6-GFK 10/20 ultramid 830a2/8401 | natur/NATURE                    | 2    |
|                                       |                     |     |                           | C   | 1   | SHTWanne 12x2/1x3pol. MGS PIN HEADER 12X2/1X3POS. MGS | PA6-GFK 10/20 ultramid 830a2/8401 | braun/BROWN                     | 1    |



THIS DRAWING IS A CONTROLLED DOCUMENT.

DATE: 12JAN2010  
 CHN: C Geiger  
 DATE: 22FEB2010  
 DATE: 22FEB2010  
 DATE: 09MAY2013

STE TE Connectivity  
 POTENTIAL DISTRIBUTION 27POS.  
 Potentialverteiler 27pol.  
 Micro Quadlock System

Customer Drawing